

## 110-43-210-10-001000

#### 110-43-210-10-001000 Information



## **Certified Quality**

Heisener's commitment to quality has shaped our processes for sourcing, testing, shipping, and every step in between. This foundation underlies each component we sell.



## 110-43-210-10-001000 Specifications

Manufacturer Part Number110-43-210-10-001000ManufacturerMill-Max Manufacturing Corp.CategoryConnectors, InterconnectsSockets for ICs, TransistorsPackage-Series110TypeDIP, 0.2" (5.08mm) Row SpacingNumber of Positions or Pins (Grid)10 (2 x 5), 6 LoadedPich - Mating0.100" (2.54mm)Contact Finish - MatingGoldContact Finish Thickness - MatingBerylium CopperMounting TypeThrough HoleFeaturesOpen FrameFeaturesSolderPich - Post0.100" (2.54mm)Contact Finish - PostSolderContact Finish - PostSolderContact Finish - PostSolderContact Finish - PostSolderContact Finish - PostGoldContact Finish - PostGoldContact Finish - PostGoldContact Finish Thickness - PostSolpin (0.76µm)Contact Finish Thicknes			
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Mounting TypeThrough HoleFeaturesOpen FrameTerminationSolderPitch - Post0.100" (2.54mm)Contact Finish - PostGold	Contact Finish Thickness - Mating	30µin (0.76µm)	
FeaturesOpen FrameTerminationSolderPitch - Post0.100" (2.54mm)Contact Finish - PostGold	Contact Material - Mating	Beryllium Copper	
TerminationSolderPitch - Post0.100" (2.54mm)Contact Finish - PostGold	Mounting Type	Through Hole	
Pitch - Post0.100" (2.54mm)Contact Finish - PostGold	Features	Open Frame	
Contact Finish - Post Gold	Termination	Solder	
	Pitch - Post	0.100" (2.54mm)	
Contact Finish Thickness - Post 30µin (0.76µm)	Contact Finish - Post	Gold	
	Contact Finish Thickness - Post	30µin (0.76µm)	
Contact Material - Post Brass Alloy	Contact Material - Post	Brass Alloy	
Housing Material Polycyclohexylenedimethylene Terephthalate (PCT), Polyester	Housing Material	Polycyclohexylenedimethylene Terephthalate (PCT), Polyester	
Operating Temperature $-55^{\circ}C \sim 125^{\circ}C$	Operating Temperature	-55°C ~ 125°C	
Report errors <sup>6</sup>			Report errors?

#### 110-43-210-10-001000 Guarantees



Quality Guarantees

We provide 90 days warranty. \* If the items you received were not in perfect quality, we would be responsible for your refund or replacement, but the items must be returned in their original condition.

# SERVICE BUARANTEE

#### **Service Guarantees**

We guarantee 100% customer satisfaction. Our experienced sales team and tech support team back our services to satisfy all our customers.

### 110-43-210-10-001000 Payment Methods





If you have any question about 110-43-210-10-001000, please do not hesitate to contact us! Website: https://www.heisener.com E-mail: salesdept@heisener.com